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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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In data sheets, where the previous Philips references is mentioned, please use the new links as shown below.

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Thank you for your cooperation and understanding,

Ampleon

VHF power MOS transistor

BLF346

FEATURES

- · High power gain
- · Easy power control
- · Good thermal stability
- · Gold metallization ensures excellent reliability.

APPLICATIONS

 Linear amplifier applications in television transmitters and transposers.

DESCRIPTION

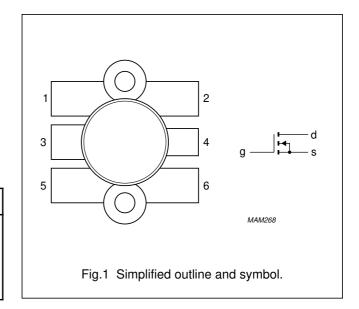
Silicon N-channel enhancement mode vertical D-MOS transistor encapsulated in a 6-lead, SOT119A flange package, with a ceramic cap. All leads are isolated from the flange. A marking code, showing gate-source voltage (V_{GS}) information is provided for matched pair applications. Refer to the General Section of the associated Data Handbook for further information.

CAUTION

This product is supplied in anti-static packing to prevent damage caused by electrostatic discharge during transport and handling. For further information, refer to Philips specs.: SNW-EQ-608, SNW-FQ-302A, and SNW-FQ-302B.

PINNING - SOT119A

PIN	DESCRIPTION						
1	source						
2	source						
3	gate						
4	drain						
5	source						
6	source						



QUICK REFERENCE DATA

RF performance in a linear amplifier.

MODE OF OPERATION	f (MHz)	V _{DS} (V)	I _D (A)	T _h (°C)	P _L (W)	G _p (dB)	d _{im} (dB) ⁽¹⁾
Class A	Class-A 224.25 28	2	70	>24	>14	–52	
Class-A		20	3	25	typ. 30	typ. 16.5	-52

Note

1. Three-tone test method (vision carrier –8 dB, sound carrier –7 dB, sideband signal –16 dB), zero dB corresponds to peak synchronization level.

WARNING

Product and environmental safety - toxic materials

This product contains beryllium oxide. The product is entirely safe provided that the BeO disc is not damaged. All persons who handle, use or dispose of this product should be aware of its nature and of the necessary safety precautions. After use, dispose of as chemical or special waste according to the regulations applying at the location of the user. It must never be thrown out with the general or domestic waste.

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LIMITING VALUES

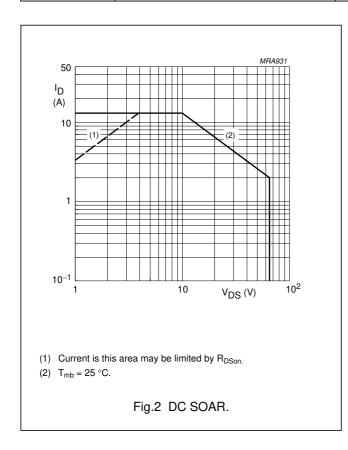
In accordance with the Absolute Maximum System (IEC 60134).

SYMBOL	PARAMETER	PARAMETER CONDITIONS				
V_{DS}	drain-source voltage		_	65	V	
V_{GS}	gate-source voltage		_	±20	٧	
I _D	drain current (DC)		_	13	Α	
P _{tot}	total power dissipation	T _{mb} ≤ 25 °C	_	130	W	
T _{stg}	storage temperature		-65	+150	°C	
Tj	junction temperature		_	200	°C	

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-mb}	thermal resistance from junction to mounting base	$T_{mb} = 25 ^{\circ}C; P_{tot} = 130 W$	1.35	K/W
R _{th mb-h}	thermal resistance from mounting base to heatsink	$T_{mb} = 25 ^{\circ}\text{C}; P_{tot} = 130 \text{W}$	0.2	K/W

3



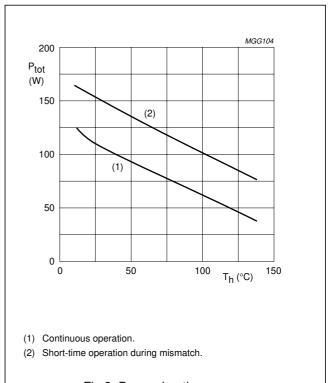


Fig.3 Power derating curves.

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CHARACTERISTICS

 T_j = 25 °C unless otherwise specified.

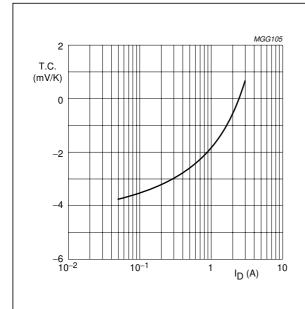
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{(BR)DSS}	drain-source breakdown voltage	V _{GS} = 0; I _D = 50 mA	65	_	_	٧
I _{DSS}	drain-source leakage current	V _{GS} = 0; V _{DS} = 28 V	_	_	2.5	mA
I _{GSS}	gate-source leakage current	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0$	_	_	1	μΑ
V _{GSth}	gate-source threshold voltage	V _{DS} = 10 V; I _D = 50 mA	2	_	4.5	٧
ΔV_{GS}	gate-source voltage difference of matched pairs	$V_{DS} = 10 \text{ V}; I_D = 50 \text{ mA}$	_	_	100	mV
9 _{fs}	forward transconductance	V _{DS} = 10 V; I _D = 5 A	3	4.2	_	S
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 5 A	-	0.2	0.3	Ω
I _{DSX}	on-state drain current	V _{GS} = 10 V; V _{DS} = 10 V	_	22	_	Α
C _{is}	input capacitance	V _{GS} = 0; V _{DS} = 28 V; f = 1 MHz	_	225	_	pF
Cos	output capacitance	V _{GS} = 0; V _{DS} = 28 V; f = 1 MHz	_	180	_	pF
C _{rs}	feedback capacitance	V _{GS} = 0; V _{DS} = 28 V; f = 1 MHz	_	25	_	pF

V_{GS} group indicator

GROUP		MITS (V)	GROUP		MITS V)
	MIN.	MAX.		MIN.	MAX.
Α	2.0	2.1	0	3.3	3.4
В	2.1	2.2	Р	3.4	3.5
С	2.2	2.3	Q	3.5	3.6
D	2.3	2.4	R	3.6	3.7
E	2.4	2.5	S	3.7	3.8
F	2.5	2.6	Т	3.8	3.9
G	2.6	2.7	U	3.9	4.0
Н	2.7	2.8	V	4.0	4.1
J	2.8	2.9	W	4.1	4.2
K	2.9	3.0	X	4.2	4.3
L	3.0	3.1	Υ	4.3	4.4
М	3.1	3.2	Z	4.4	4.5
N	3.2	3.3			

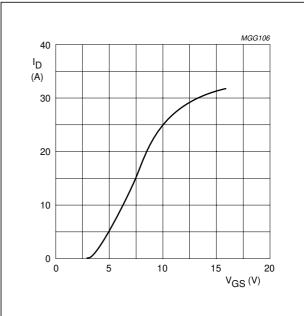
VHF power MOS transistor

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 $V_{DS} = 10 \text{ V}.$

Fig.4 Temperature coefficient of gate-source voltage as a function of drain current; typical values.



 V_{DS} = 10 V; T_j = 25 °C.

Fig.5 Drain current as a function of gate-source voltage; typical values.

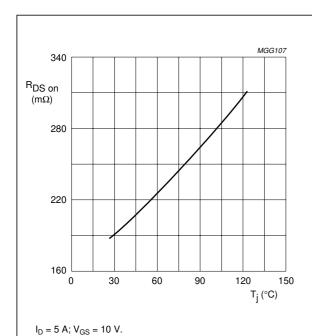
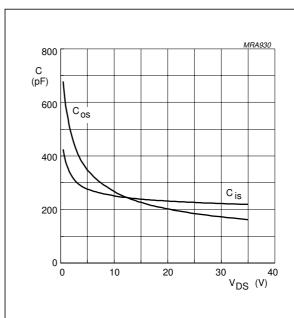


Fig.6 Drain-source on-state resistance as a function of junction temperature; typical values.



 $V_{GS} = 0$; f = 1 MHz.

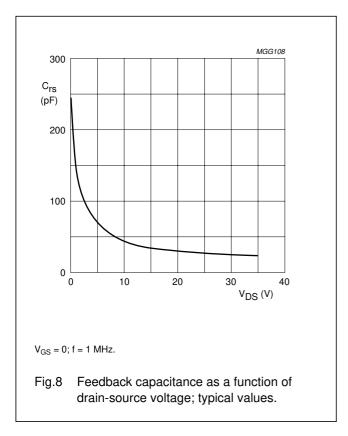
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Fig.7 Input and output capacitance as functions of drain-source voltage; typical values.

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APPLICATION INFORMATION

RF performance in a linear amplifier (common source class-A circuit). $R_{th\ mb-h}=0.2\ K/W;\ Z_L=1.1+j0.2\ \Omega$ unless otherwise specified.

MODE OF OPERATION	f (MHz)	V _{DS} (V)	I _D (A)	T _h (°C)	P _{o sync} (W)	G _p (dB)	d _{im} (dB) ⁽¹⁾
Class-A				70	>24	>14	-52
	224.25	28	3	25	typ. 30	typ. 16.5	-52
	224.25			70	typ. 20	typ. 14.5	– 55
				25	tvp. 22	tvp. 15	-55

Note

1. Three-tone test method (vision carrier –8 dB, sound carrier –7 dB, sideband signal –16 dB), zero dB corresponds to peak synchronization level.

Ruggedness in class-A operation

The BLF346 is capable of withstanding a load mismatch corresponding to VSWR = 50: 1 through all phases under the following conditions: $V_{DS} = 28 \text{ V}$; f = 225 MHz at rated output power.

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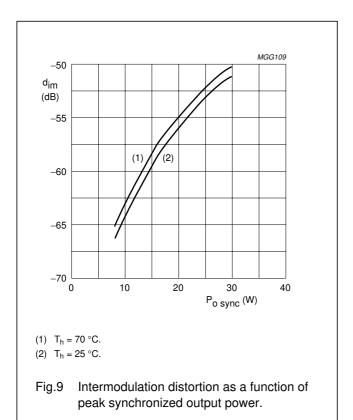


Fig.10 Test circuit for class-A operation at f = 225 MHz.

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List of components (see Figs 10 and 11).

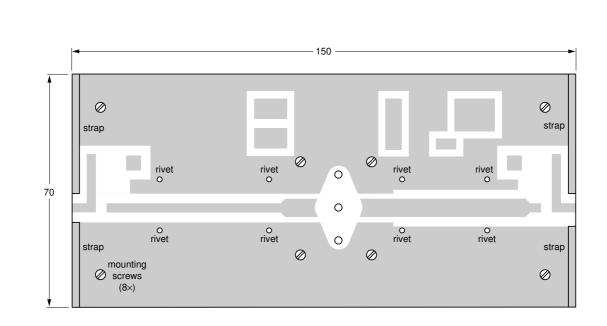
COMPONENT	DESCRIPTION	VALUE	DIMENSIONS	CATALOGUE NO.		
C1	film dielectric trimmer	2 to 18 pF		2222 809 09003		
C2	multilayer ceramic chip capacitor; note 1	10 pF, 500 V				
C3, C15, C16	film dielectric trimmer	4 to 40 pF		2222 809 08002		
C4, C5	multilayer ceramic chip capacitor; note 1	56 pF, 500 V				
C6, C12	multilayer ceramic chip capacitor; note 1	680 pF, 500 V				
C7, C8, C9	multilayer ceramic chip capacitor	100 nF, 50 V		2222 852 47104		
C10, C11	multilayer ceramic chip capacitor; note 1	43 pF, 500 V				
C13	electrolytic capacitor	10 μF, 63 V		2222 030 38109		
C14	multilayer ceramic chip capacitor; note 1	27 pF, 500 V				
L1	4 turns enamelled 0.7 mm copper wire	42.4 nH	length 4 mm; int. dia. 3 mm; leads 2 × 5 mm			
L2	stripline; note 2	50 Ω	length 49 mm; width 2.8 mm			
L3, L4	stripline; note 2	31 Ω	length 11.5 mm; width 6 mm			
L5	2 turns enamelled 1.5 mm copper wire	18.7 nH	length 8 mm; int. dia. 4 mm; leads 2 × 5 mm			
L6	grade 3B Ferroxcube RF choke			4312 020 36642		
L7	stripline; note 2	31 Ω	length 40 mm; width 6 mm			
L8	3 turns enamelled 1.5 mm copper wire	28.8 nH	length 8 mm; int. dia. 4 mm; leads 2 × 5 mm			
R1	metal film resistor	1 kΩ, 0.4 W		2322 151 71002		
R2	metal film resistor	100 kΩ, 0.4 W		2322 151 71004		
R3	10 turns cermet potentiometer	100 Ω				
R4	metal film resistor	316 kΩ, 0.4 W		2322 153 53161		
R5	metal film resistor	10 Ω, 0.4 W		2322 153 51009		

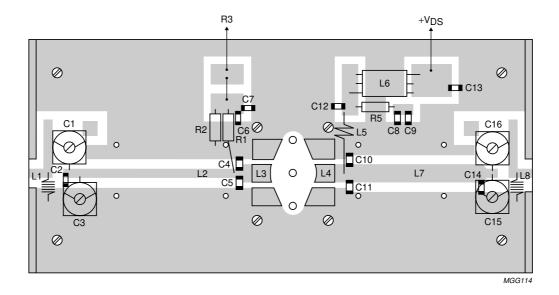
Notes

- 1. American Technical Ceramics capacitor, type 100B or other capacitor of the same quality.
- 2. The striplines are on a double copper-clad printed-circuit board with epoxy fibre-glass dielectric (ε_r = 4.5); thickness $^{1}\!\!/_{16}$ inch.

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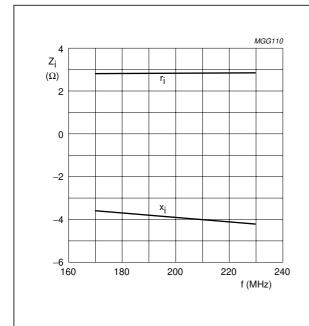
Dimensions in mm.

The circuit and components are situated on one side of the printed-circuit board, the other side being fully metallized, to serve as a ground plane. Earth connections are made by means of copper straps and hollow rivets.

Fig.11 Component layout for 225 MHz class-A test circuit.

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Class-A operation; V_{DS} = 28 V; I_{D} = 3 A; P_{L} = 30 W; T_{h} = 70 $^{\circ}C.$

Fig.12 Input impedance as a function of frequency (series components); typical values.

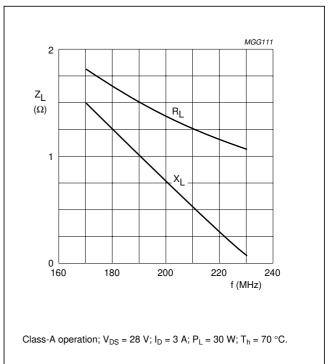
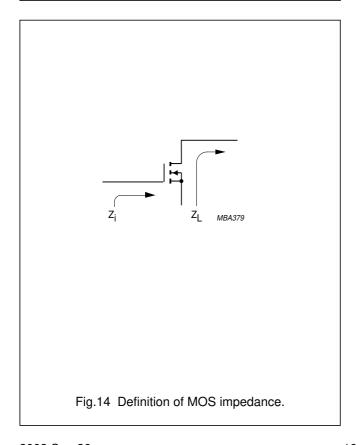
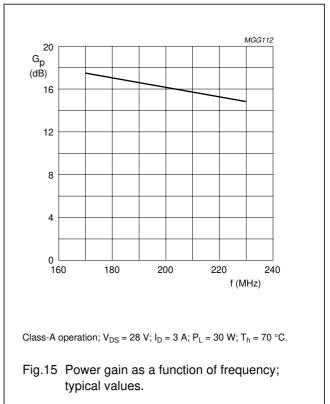


Fig.13 Load impedance as a function of frequency (series components); typical values.





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BLF346 scattering parameters

 $V_{DS} = 28 \text{ V}; I_D = 3000 \text{ mA}; \text{ note 1}.$

f (MHz)		§11	S	21	S	12	S ₂₂		
i (IVIITIZ)	s ₁₁	∠Φ	s ₂₁	∠Φ	s ₁₂	∠Φ	S ₂₂	∠Φ	
100	0.91	-178.9	2.12	67.7	0.01	-0.6	0.88	-177.3	
105	0.91	-179.0	2.01	66.6	0.01	-0.4	0.88	-177.4	
110	0.92	-179.1	1.91	65.5	0.01	-0.1	0.88	-177.4	
115	0.92	-179.2	1.81	64.5	0.01	0.2	0.88	-177.4	
120	0.92	-179.3	1.72	63.5	0.01	0.5	0.89	-177.4	
130	0.92	-179.5	1.56	61.5	0.01	1.3	0.89	-177.5	
140	0.92	-179.7	1.43	59.6	0.01	2.5	0.89	-177.5	
150	0.93	-179.9	1.31	58.0	0.01	4.1	0.90	-177.6	
160	0.93	180.0	1.21	56.3	0.01	6.0	0.90	-177.7	
170	0.93	179.8	1.12	54.7	0.01	8.2	0.90	-177.8	
180	0.93	179.5	1.04	53.0	0.01	10.5	0.91	-177.9	
190	0.93	179.3	0.97	51.2	0.01	13.0	0.91	-178.0	
200	0.94	179.1	0.91	49.6	0.01	15.7	0.91	-178.1	
225	0.94	178.5	0.77	46.1	0.01	23.9	0.92	-178.5	
250	0.95	178.0	0.66	43.3	0.01	33.6	0.93	-178.9	
275	0.95	177.4	0.58	40.1	0.01	43.6	0.94	-179.3	
300	0.95	176.7	0.50	37.5	0.01	51.8	0.94	-179.7	
350	0.96	175.5	0.40	33.5	0.01	65.7	0.95	179.4	
400	0.97	174.8	0.32	30.6	0.01	74.5	0.96	178.4	
450	0.97	173.6	0.27	27.7	0.01	80.0	0.97	177.4	
500	0.98	172.5	0.22	25.8	0.02	83.0	0.97	176.4	
600	0.99	170.3	0.16	24.0	0.02	86.7	0.98	174.6	
700	1.00	168.2	0.13	24.7	0.03	88.5	0.99	172.8	
800	1.05	165.0	0.10	27.6	0.03	90.1	0.99	170.9	
900	1.03	158.5	0.09	31.5	0.04	91.0	1.00	168.9	
1000	1.00	156.6	0.08	38.7	0.04	92.1	1.00	167.1	

Note

^{1.} For more extensive s-parameters see internet: http://www.semiconductors.philips.com/markets/communications/wirelesscommunications/broadcast

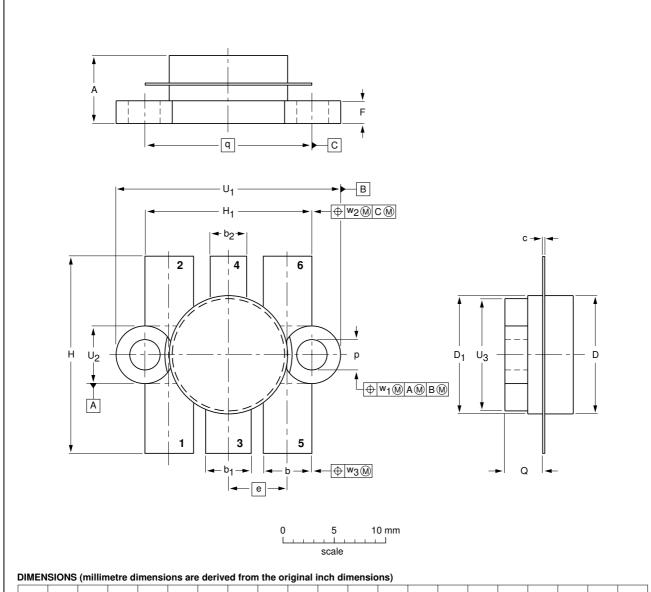
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PACKAGE OUTLINE

Flanged ceramic package; 2 mounting holes; 6 leads

SOT119A



UNIT	Α	b	b ₁	b ₂	С	D	D ₁	е	F	Н	Н1	р	Q	q	U ₁	U ₂	U ₃	w ₁	w ₂	w ₃
mm	7.39 6.32	5.59 5.33	5.34 5.08	4.07 3.81	0.15 0.10	12.86 12.59	12.83 12.57	6.48			18.55 18.28		4.57 4.06	18.42	24.89 24.64	6.48 6.22	12.32 12.07	0.25	0.51	0.25
inches	0.291 0.249	0.220 0.210	0.210 0.200	0.160 0.150	0.006 0.004	0.505 0.496	0.505 0.495	0.255	0.100 0.090	0.865 0.835	0.730 0.720	0.130 0.120	0.180 0.160	0.725	0.980 0.970	0.255 0.245	0.485 0.475	0.010	0.020	0.010

OUTLINE		REFER	EUROPEAN	ICCUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT119A						99-03-29	

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